



Ultra-low Power Bluetooth Audio Platform for TWS Applications with Hybrid ANC

CONTACT US

Company: Bestechnic (Shanghai) Co., Ltd. (“**BES**”)

Address: 2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)

Phone: (86)21 6877 1788

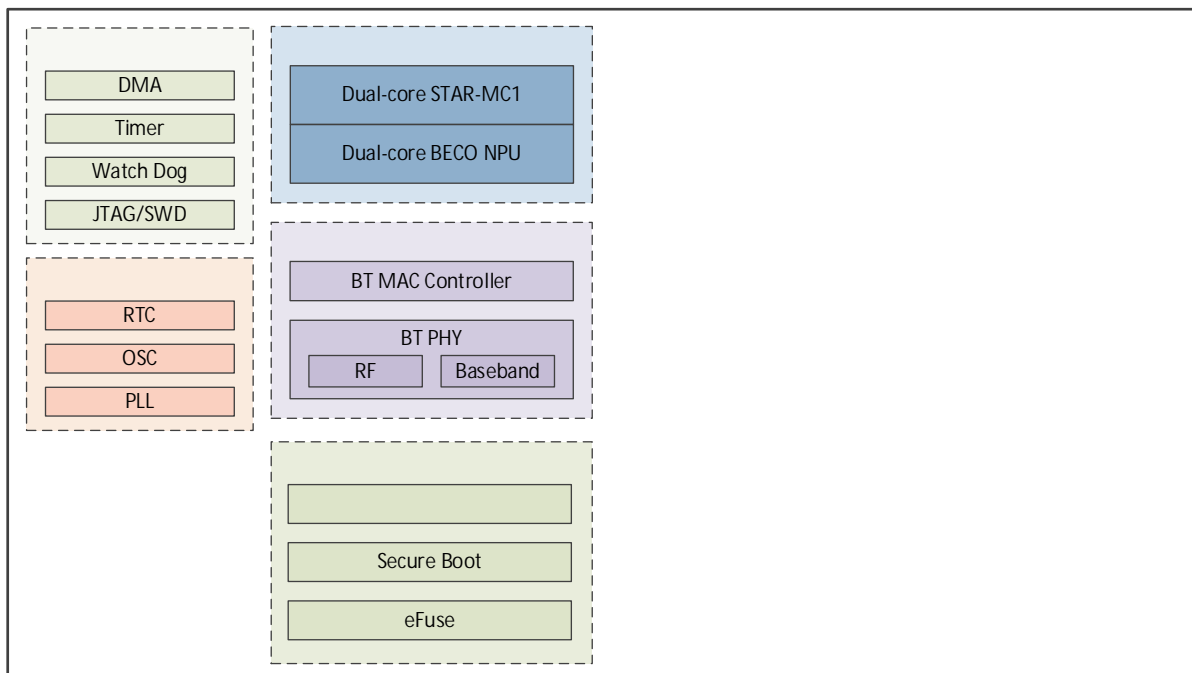
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The BES2700IHC is an ultra-low power Bluetooth audio SoC. The platform incorporates a CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces. This combination minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem and a Power Management Unit (PMU) with an integrated charger. The highly integrated design is optimized through the use of IBRT technology, a BES patented sniffing technique that incorporates Forward Error Correction (FEC) for enhanced RF performance in TWS systems.



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CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 512 KB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Audio & Voice Features	2x DACs
	2x ADCs
Peripheral Interfaces	SDIO/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO/GPADC.....
Package	50-pin QFN

* The content in the table is subject to change without notice.